PIN ONE REFERENCE

2X \ \accord \ 0.10 \ \ C

0.10 C

0.08 С

> Α B **b1**

NOTE 3

**EDGE OF PACKAGE** 

С 0.05

**DETAIL A** 

**Bottom View** 

(Optional)

0.10 С

Ф

2X |  $\bigcirc$  | 0.10 | C



**TOP VIEW** 

DETAIL B

SIDE VIEW

**BOTTOM VIEW** 

MOLD CMPD

Α1

A B

Ε

C SEATING PLANE

CA

NOTE 3

**EXPOSED Cu** 

А3

С 0.05

**DETAIL B** 

Side View

(Optional)

е

**b** 5X 0.10

Ф

DETAIL A  $\emptyset$  D2

**DATE 06 FEB 2006** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. DIMENSION b APPLIES TO PLATED
  TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL.
  4. COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.
  TERMINAL b MAY HAVE MOLD COMPOUND
- MATERIAL ALONG SIDE EDGE.
  6. DETAILS A AND B SHOW OPTIONAL VIEWS FOR END OF TERMINAL LEAD AT EDGE OF PACKAGE AND SIDE EDGE OF PACKAGE.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3	0.20 REF		
b	0.20	0.25	0.30
b1	0.30	0.35	0.40
D	2.00 BSC		
D2	0.40	0.50	0.60
Е	2.20 BSC		
е	0.65 BSC		
L	0.30	0.35	0.40
11	0.00	0.05	0.10

## **GENERIC** MARKING DIAGRAM\*

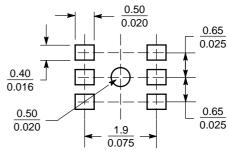


= Specific Device Code

= Date Code Μ

\*This information is generic. Please refer to device data sheet for actual part marking.

## **SOLDERING FOOTPRINT\***



SCALE 10:1

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON04199D	Electronic versions are uncontrolle	
STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document versions are uncontrolled except	' '
NEW STANDARD:		"CONTROLLED COPY" in red.	
DESCRIPTION:	DFN6 2 X 2.2 X 0.9 X 0.65P		PAGE 1 OF 2



<b>DOCUMENT</b>	NUMBER:
98AON04199	D

## PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY J. HOSKINS.	30 JAN 2001
Α	REMOVED DIM'S E,F,K,M,N,P,Q AND R. UPDATED VIEW. REQ. BY M. JONES.	23 MAY 2001
В	REMOVED IDENT PIN. SWAPPED THE TOP LEFT AND RIGHT PAD LOCATIONS. REQ. BY M. SALEH.	13 SEP 2001
С	CHANGED DESCRIPTION FROM 2 X 2 TO 2 X 2.2. CHANGE MARKING DIAGRAM. REQ. BY K. OPPEN.	27 JUN 2003
D	CHANGED MARKING DIAGRAM. REQ. BY S. RIGGS.	30 JUL 2003
E	ADDED "U' DIMENSION TO DIMENSION TABLE. REQ. BY K. OPPEN.	03 MAR 2004
F	CHANGED DEVICE DESCRIPTION FROM QFN TO DFN. REQ. BY A. GARLINGTON.	02 NOV 2005
G	CHANGED DRAWING FORMAT TO STANDARD FORMAT. REQ. BY B. LOFTS.	06 FEB 2006

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights or the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.